Product Change Notification: CENO-10JZGR405

Date:

15-Jun-2026

Product Category:

Linear Op Amps, Linear Regulators

Notification Subject:

CCB 8337 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP1799T-5002H/TT, MCP1799T-3302H/TT, MCP6476UT-E/OT, MCP6006RT-E/OT, MCP6006T-E/OT, MCP6476T-E/OT, MCP6476RT-E/OT, MCP6006UT-E/OT, MCP6486RT-E/OT, MCP6486T-E/OT, MCP6496RT-E/OT, MCP6496UT-E/OT, MCP6496T-E/OT and MCP6486UT-E/OT catalog part numbers (CPN) available in 3L and 5L SOT-23 (1.3mm) packages at MTAI assembly site

Affected CPNs:

CENO-10JZGR405_Affected_CPN_06152026.pdf
CENO-10JZGR405_Affected_CPN_06152026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP1799T-5002H/TT, MCP1799T-3302H/TT, MCP6476UT-E/OT, MCP6006RT-E/OT, MCP6006T-E/OT, MCP6476T-E/OT, MCP6476RT-E/OT, MCP6006UT-E/OT, MCP6486RT-E/OT, MCP6486T-E/OT, MCP6496RT-E/OT, MCP6496UT-E/OT, MCP6496T-E/OT and MCP6486UT-E/OT catalog part numbers (CPN) available in 3L and 5L SOT-23 (1.3mm) packages at MTAI assembly site

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	84-3J (PFAS-free)	84-3J (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 September 2026 (date code: 2638)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	**September 2026**				
Work Week	23	24	25	26	27		36	37	38	39	40
Qual Report Availability			x								
Final PCN Issue Date			x								
Estimated Implementation Date									x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

June 15, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-10JZGR405 Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

MCP1799T-5002H/TT

MCP1799T-3302H/TT

MCP6476UT-E/OT

MCP6006RT-E/OT

MCP6006T-E/OT

MCP6476T-E/OT

MCP6476RT-E/OT

MCP6006UT-E/OT

MCP6486RT-E/OT

MCP6486T-E/OT

MCP6496RT-E/OT

MCP6496UT-E/OT

MCP6496T-E/OT

MCP6486UT-E/OT

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CENO-10JZGR405

Date:
January 14, 2025

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP1799T-5002H/TT, MCP1799T-3302H/TT, MCP6476UT-E/OT, MCP6006RT-E/OT, MCP6006T-E/OT, MCP6476T-E/OT, MCP6476RT-E/OT, MCP6006UT-E/OT, MCP6486RT-E/OT, MCP6486T-E/OT, MCP6496RT-E/OT, MCP6496UT-E/OT, MCP6496T-E/OT and MCP6486UT-E/OT catalog part numbers (CPN) available in 3L and 5L SOT-23 (1.3mm) packages at MTAI assembly site.
This is a qualification by similarity (QBS).

MICROCHIP
PACKAGE QUALIFICATION REPORT

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP1799T-5002H/TT, MCP1799T-3302H/TT, MCP6476UT-E/OT, MCP6006RT-E/OT, MCP6006T-E/OT, MCP6476T-E/OT, MCP6476RT-E/OT, MCP6006UT-E/OT, MCP6486RT-E/OT, MCP6486T-E/OT, MCP6496RT-E/OT, MCP6496UT-E/OT, MCP6496T-E/OT and MCP6486UT-E/OT catalog part numbers (CPN) available in 3L and 5L SOT-23 (1.3mm) packages at MTAI assembly site. This is a qualification by similarity (QBS).
CCB No.	7276 (Qual Date: January 14, 2025) and 8337
CN	E000252896
QUAL ID	R2401511 Rev. A
MP CODE	DFBE1YC8XAA0
Part No.	MCP4706A0T-E/CH
Bonding No.	BD-002754 Rev. 01

Package

Type	6L SOT-23

Lead Frame

Paddle size	72 x 41 mils
Material	A194
Surface	Ag single ring Plated
Process	Stamped
Lead Lock	No
Part Number	10100607
Treatment	BOT

Material

Epoxy	84-3J
Wire	CuPdAu
Mold Compound	G600V
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI253301572.000	TMPE224408368.430	2446DGP
MTAI253400843.000	TMPE224408368.430	2447ES7
MTAI253400897.000	TMPE224408368.430	2447EUC

Result [X] Pass [ ] Fail [ ] _____

6L SOT-23 assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 1)	**Electrical Test:** +25°C and 125°C System: J750_MSO	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 125°C System: J750_MSO		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 125°C System: J750_MSO		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750_MSO		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt :** Vdd= 5.0 Volts System: HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 125°C System: J750_MSO		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. System: TPS Bake Oven **Electrical Test:** +25°C and 125°C System: J750_MSO	JESD22-A103	 135(0)	0/135 0/135	 Pass	45 units / lot
Bond Strength **Data Assembly**	Wire Pull (>3.00 grams) Bond Shear (>15.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) bonds	0/30 0/30	Pass Pass	